

Date: February 11, 2003



In re Application of: Haruaki SUE et al.

Serial No. 09/966,630

Filed: November 9, 2001

For: CYCLOPENTYLENE COMPOUND AND INTERMEDIATE THEREOF, EPOXY RESIN COMPOSITION, MOLDING MATERIAL, AND RESIN ENCAPSULATED ELECTRONIC DEVICE

ASSISTANT COMMISSIONER FOR PATENTS

Box: NO FEE AMENDMENT

Washington, D. C. 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- [] Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.
- [] A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is hereby claimed.
- [XXX] No additional fee is required.

The fee has been calculated as shown below:

| (COL. 1) | | (COL. 2) | | (COL. 3) | | SMALL ENTITY | | OTHER THAN A SMALL ENTITY | |
|---|----|-------------|----|----------|---|--------------|--|---------------------------|--|
| CLAIMS | | HIGHEST NO. | | PRESENT | | ADDIT. OR | | ADDIT. | |
| REMAINING | | PREVIOUSLY | | EXTRA | | RATE | | RATE | |
| AFTER | | PAID FOR | | | | | | | |
| AMENDMENT | | | | | | | | | |
| TOTAL * | 28 | MINUS ** | 28 | = | 0 | X 9 = \$ | | X 18 = \$ | |
| INDEP. * | 9 | MINUS *** | 9 | = | 0 | X 42 = \$ | | X 34 = \$ | |
| [] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM | | | | | | X140 = \$ | | X230 = \$ | |

TOTAL
ADDIT. FEE \$ 0 OR TOTAL \$

- * If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.
- ** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.
- *** If the "Highest No. Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space.
- The "Highest No. Previously Paid For" (Total or Independent) is the highest number found from the equivalent box in Col. 1 of a prior Amendment or the number of claims originally filed.

- [] Please charge my Deposit Account No. 501281 in the amount of \$. A duplicate copy of this sheet is attached.
- [] A check (No.) in the amount of \$ is attached.
- [XXX] The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 501281. A duplicate copy of this sheet is attached.

- [XX] Any filing fees under 37 CFR 1.16 for the presentation of extra claims.
- [XX] Any patent application processing fees under 37 CFR 1.17.

Joerg-Uwe Szapl
Reg. No. 31,799

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Haruaki SUE et al.) Atty. Docket: **TM&K 0014**
Serial No. 09/986,630)
Filed: November 9, 2001)
For: CYCLOPENTYLENE COMPOUND)
AND INTERMEDIATE THEREOF,)
EPOXY RESIN COMPOSITION,)
MOLDING MATERIAL, AND)
RESIN-ENCAPSULATED) Date: February 11, 2003
ELECTRONIC DEVICE)

PRELIMINARY AMENDMENT (B)

Box: NO FEE AMENDMENT
Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

Kindly amend the above-captioned application as follows:

IN THE CLAIMS:

Amend claims 17 and 26 to read as follows:

17. (Amended) A compound which is a cooligomer represented by the
following general formula (I):